



Material Content Data Sheet



Sales Product Name	TLE9879-2QXA40			Issued	29. November 2018			
MA#	MA002641586							
Package	PG-VQFN-48-31			Weight*	129.96 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.821	3.71	3.71	37093	37093
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		551	
	non noble metal	iron	7439-89-6	1.433	1.10		11028	
wire	non noble metal	copper	7440-50-8	58.193	44.77	45.94	447766	459483
	non noble metal	copper	7440-50-8	0.619	0.48	0.48	4765	4765
	encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1394
encapsulation	plastics	epoxy resin	-	7.668	5.90		59004	
	inorganic material	silicondioxide	60676-86-0	52.531	40.42	46.46	404198	464596
	leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19978
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4723	4723
glue	plastics	epoxy resin	-	0.280	0.22		2153	
	noble metal	silver	7440-22-4	0.937	0.72	0.94	7209	9362
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com